

ABSTRACT

A polishing liquid for polishing a member to be polished containing a resin, the polishing liquid containing abrasive grains containing cerium oxide and an ether compound having a hydroxy group.

5 A polishing method including polishing a member to be polished containing a resin by using the above-described polishing liquid. A method for manufacturing a component, including obtaining a component by using a polished member polished by the above-described polishing method. A method for manufacturing a semiconductor
10 component, including obtaining a semiconductor component by using a polished member polished by the above-described polishing method.

No Suitable Figure